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TRANSMITTAL FORM (to be used for all correspondence after initial filing)	Application Number	10/032,564	
	Filing Date	January 2, 2002	
	First Named Inventor	Yasutoshi OKUNO et al.	
	Group Art Unit	2833	
	Examiner Name	M. Estrada	
Total Number of Pages in This Submission		Attorney Docket Number	740819-725

ENCLOSURES (check all that apply)

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SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm or Individual name	<u>Donald R. Studebaker (Reg. No. 32,815)</u> Nixon Peabody LLP 8180 Greensboro Drive Suite 800 McLean, VA 22102
Signature	
Date	August 6, 2002

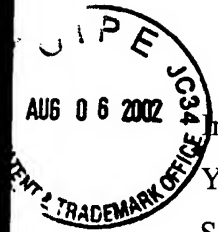
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#5/Amend A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re Patent Application of)
Yasutoshi OKUNO et al.)
Serial No. 10/032,564)
Filed: January 2, 2002)
For: METHOD FOR FABRICATING)
SEMICONDUCTOR DEVICE)

Group Art Unit: 2823

Examiner: Michelle ESTRADA

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed May 8, 2002, Applicants respectfully submit the following amendments and remarks in connection with the above-captioned matter.

IN THE CLAIMS:

Please amend claims 1 and 3 as follows:

sub B1
A1
1. (Amended) A method for fabricating a semiconductor device including a capacitor device having a lower electrode, a capacitor dielectric film formed on said lower electrode and an upper electrode formed on said capacitor dielectric film, comprising a step of:

forming a conducting film to be formed into said lower electrode including sub-steps of:
depositing a lower conducting film on a substrate by sputtering; and
depositing an upper conducting film directly on said lower conducting film by CVD.

sub B2
A2
3. (Amended) A method for fabricating a semiconductor device including a capacitor device having a lower electrode, a capacitor dielectric film formed on said lower electrode and an upper electrode formed on said capacitor dielectric film, comprising a step of:

forming a conducting film to be formed into said upper electrode including sub-steps of:
depositing a lower conducting film on said capacitor dielectric film by sputtering; and
depositing an upper conducting film directly on said lower conducting film by CVD.